Product End-of-Life Disassembly Instructions

Product Category: Storage Enclosures
Marketing Name / Model [List multiple models if applicable.]
HP 3Par F200 Storage System (QL226B)
HP 3Par F400 Storage System (QL227B)
Name / Model #4
Name / Model #5

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.
1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	F200: 7 to 11 F400: 13 to 21
Batteries	All types including standard alkaline and lithium coin or button style batteries	F200:1 to 2 F400: 2 to 4
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height		F200: 4 F400: 8
External electrical cables and cords		F200: 2 F400: 4
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)		0

Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0
Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Phillips Screwdriver	#1
Screwdriver	Slot tip
Description #3	
Description #4	
Description #5	

3.0 Product Disassembly Process

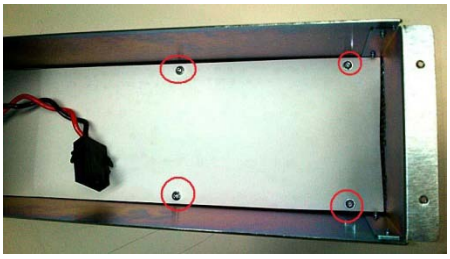
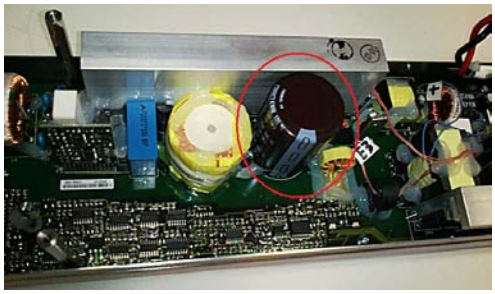
3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

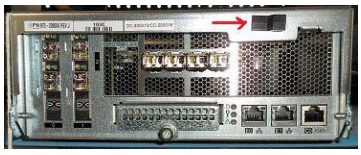
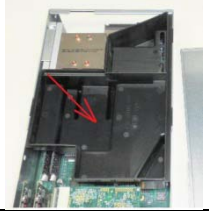
1. F200/F400 Storage System
2. Remove the power supplies from Back side
3. Remove the Controller Node(s) from Back side
4. Remove the Fan Assemblies from the Front side
5. Remove the LED status PCBA from the Front side
6. Remove the Center Plane from chassis
7.
8.
9.
10.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).

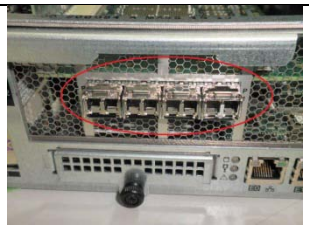
Disassembly Instructions:
Insure the system is shut down, and power cables disconnected.

Disassembling F200/F400 Node Power Supplies (PS):		
Remove the power supply from the Chassis by pushing the latch to the right and pulling the handle away from the power supply.	Remove the back-up battery by loosening the two thumb screws	Lift battery out of the PS case and disconnect the cable by lifting up on the tab.

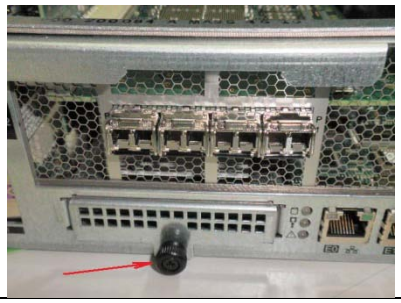
		
Remove 6 screws from each side of the PS, and 1 screw from the bottom 	Remove 4 screws from the insulator and remove the insulator 	Remove the Capacitors  

Disassembling F200/F400 Controller Node:		
Remove Node from the chassis by pushing on the latch to the right and swing the handle away from the chasis. Pull Node straight out. 	Remove top cover, lift from mid section and rotate back. Remove the plastic tray.  	Remove FC/riser card from Node. Remove the front clip and one mounting screw.  Remove the SFPs from the HBA and pull the card out from the base PCBA.

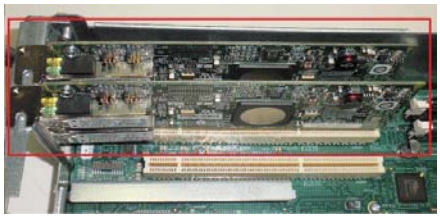
PSG instructions for this template are available at EL-MF877-01



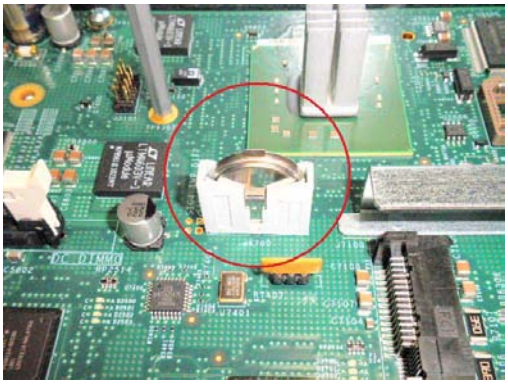
Remove Node Drive by loosening thumb screw and pulling the drive assembly straight out.



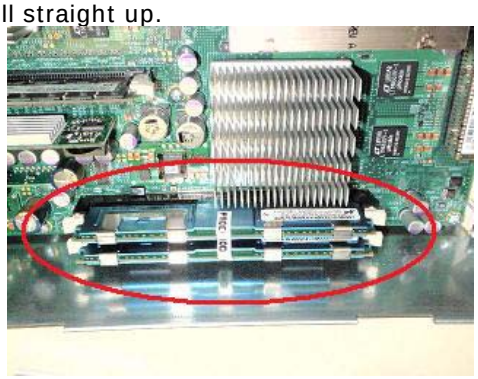
If half height HBAs are present, remove by pulling straight up.



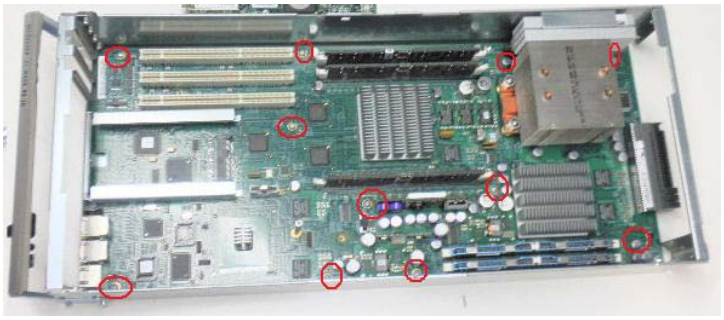
Remove the battery

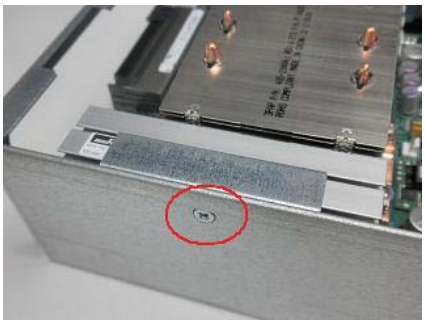


Remove DIMMs by opening the two latches on each DIMM and pull straight up.



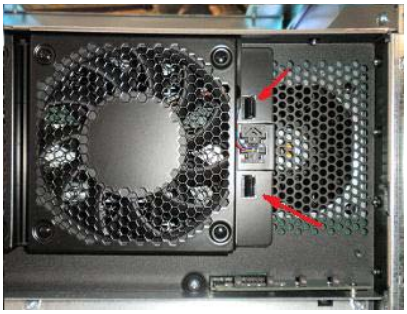
Remove the hold down screws for the PCBA and one on the side. Pull PCBA straight up.

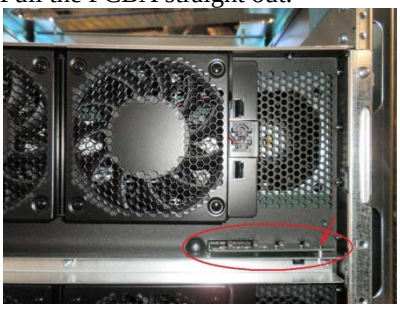




Disassembling F200/F400 Node Fan Assembly:		
Remove the front bezel if one is installed.	Push on the two tabs and pull the fan away from the chassis.	

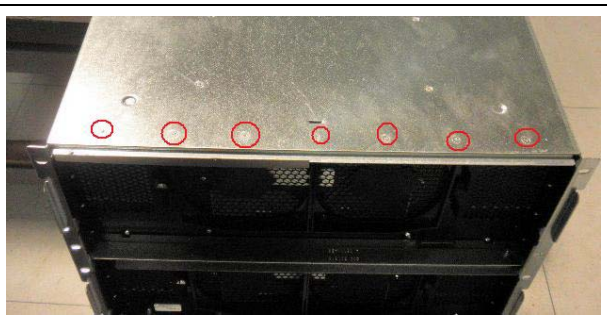
PSG instructions for this template are available at EL-MF877-01

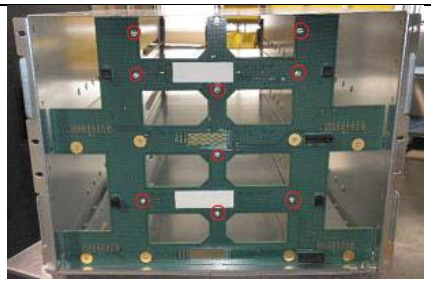
		

Disassembling F200/F400 Node LED Status PCBA:		
Remove the front bezel if one is installed.	Pull the PCBA straight out. 	

Disassembling F200/F400 Node Center Plane PCBA:		
Remove all Frus/components from the chassis. F400 chassis is shown. 	Remove the center rail, 3 nuts. 	Remove the front shroud screws, 8x. 
Remove all the 7 top screws and 8 screws on each side.	Remove the Center Plane screws and pull out center plane PCBA.	

PSG instructions for this template are available at EL-MF877-01





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